Laurier DS-4000
Device Sorter

The Laurier DS-4000 is a high precision die sorter with the flexibility to place a variety of devices including Flip Chip, WLCSP, BGA's, MEMS, GaAS, Laser Bars and bare silicon.

- Top surface and backside inspection
- Pick and Place into tape reel, waffle pack, Gel-Pak®, film frame, hoop, JEDEC tray or custom carriers
- Quick change over
- Flip or no flip to the output carrier with the click of a button
- Component size from 0.2 mm to 25 mm
- Accuracy of ± 25 μm
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Technical Specifications for Laurier DS-4000

**Speed**
- Places devices at up to 4800 UPH

**Accuracy**
- Placement repeatability of ± 25 μm

**Flexibility**
- Quick change between tape reel, wafer pack, Gel-Pak®, film frame, hoop, JEDEC tray or custom carrier.
- Device changeover in < 5 minutes
- Flip or no flip selectable in software
- Standard die size range from .2 mm to 45 mm

**Inspection Capability**
- Detects defects down to 1/80th of die size
- Ink dot inspection
- Bump inspection
- Chip defect inspection
- Backside mark verification

**Configurations**

**Input**
- Auto loads up to 200mm wafer from cassettes
- Programmable stretch option
- Programmable push up needles
- Programmable lighting and zoom
- Barcode reader for map download

**Output**
- Array of fourteen 2” waffle packs or Gel-Paks, or four 4” trays
- Laser bar stacking and unstacking
- Tape Reel
  - Easily adjust tape width from 8 to 24 mm
  - Programmable tape index pitch
  - Programmable Inverter
  - Rejct die removal / replacement system
  - Level wind supply reel reduces changeover time

**Facilities**
- 200/230 VAC
- 85 PSI

**Cleanroom**
- Class 10000

**Standards Compliance**
- Complies with CE, SEMI S2 & S8 and NFPA79 standards

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Besi Die Handling is a Product Division of BE Semiconductor Industries N.V., which is publicly listed at NASDAQ (USA) and the Amsterdam (The Netherlands) Stock Exchange. (NASDAQ: BESI Amsterdam Stock Exchange: BESI) Website: www.besi.com

Information is subject to change without notice.